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(12) **United States Design Patent**
Masuda

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(54) **SEMICONDUCTOR DEVICE**

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(**) Term: **14 Years**

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(22) Filed: **Feb. 6, 2014**

Related U.S. Application Data

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(30) **Foreign Application Priority Data**

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Dec. 28, 2010 (JP) D.2010-031447
Dec. 28, 2010 (JP) D.2010-031448

(51) **LOC (10) Cl.** **13-03**
(52) **U.S. Cl.**
USPC **D13/182**
(58) **Field of Classification Search**
USPC D13/182
CPC . H05K 1/0228; H05K 1/0245; H05K 1/0236; H05K 1/0263; H01L 21/02433; H01L 29/04
See application file for complete search history.

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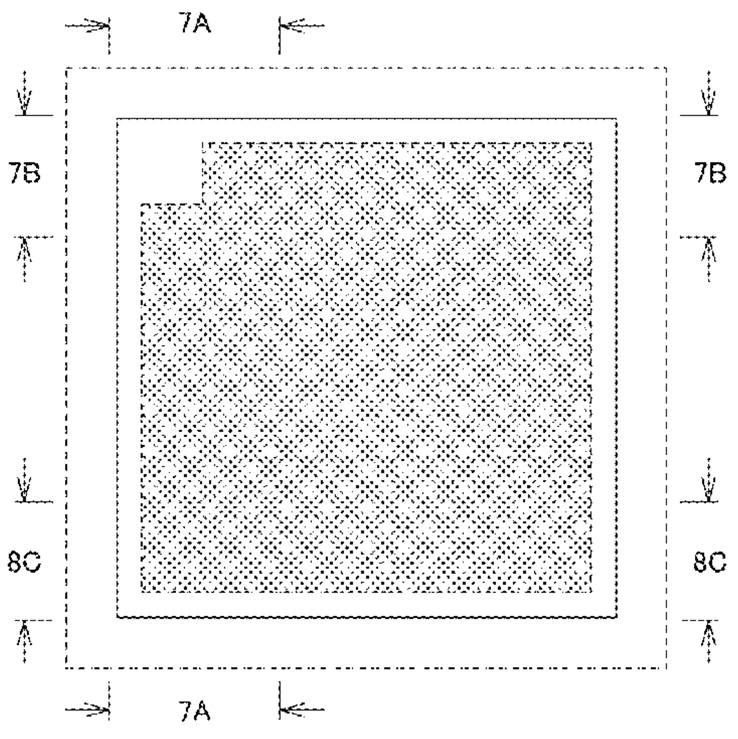
(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. **1** is a front view of a semiconductor device showing my new design;
FIG. **2** is a rear view thereof;
FIG. **3** is a top plan view thereof;
FIG. **4** is a bottom plan view thereof;
FIG. **5** is a right side view thereof;
FIG. **6** is a left side view thereof;
FIG. **7** is an enlarged perspective view showing the area defined by indicia **7**A and **7**B of FIG. **1** thereof; and,
FIG. **8** is an enlarged perspective view showing the area defined by indicia **7**A and **8**C of FIG. **1** thereof.
The broken line showing is for illustrative purpose only and forms no part of the claimed design.

1 Claim, 4 Drawing Sheets



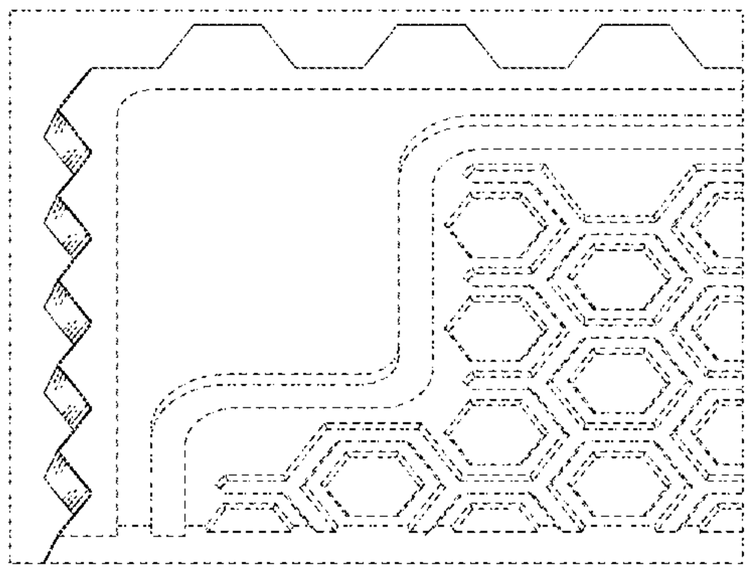


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FIG.1

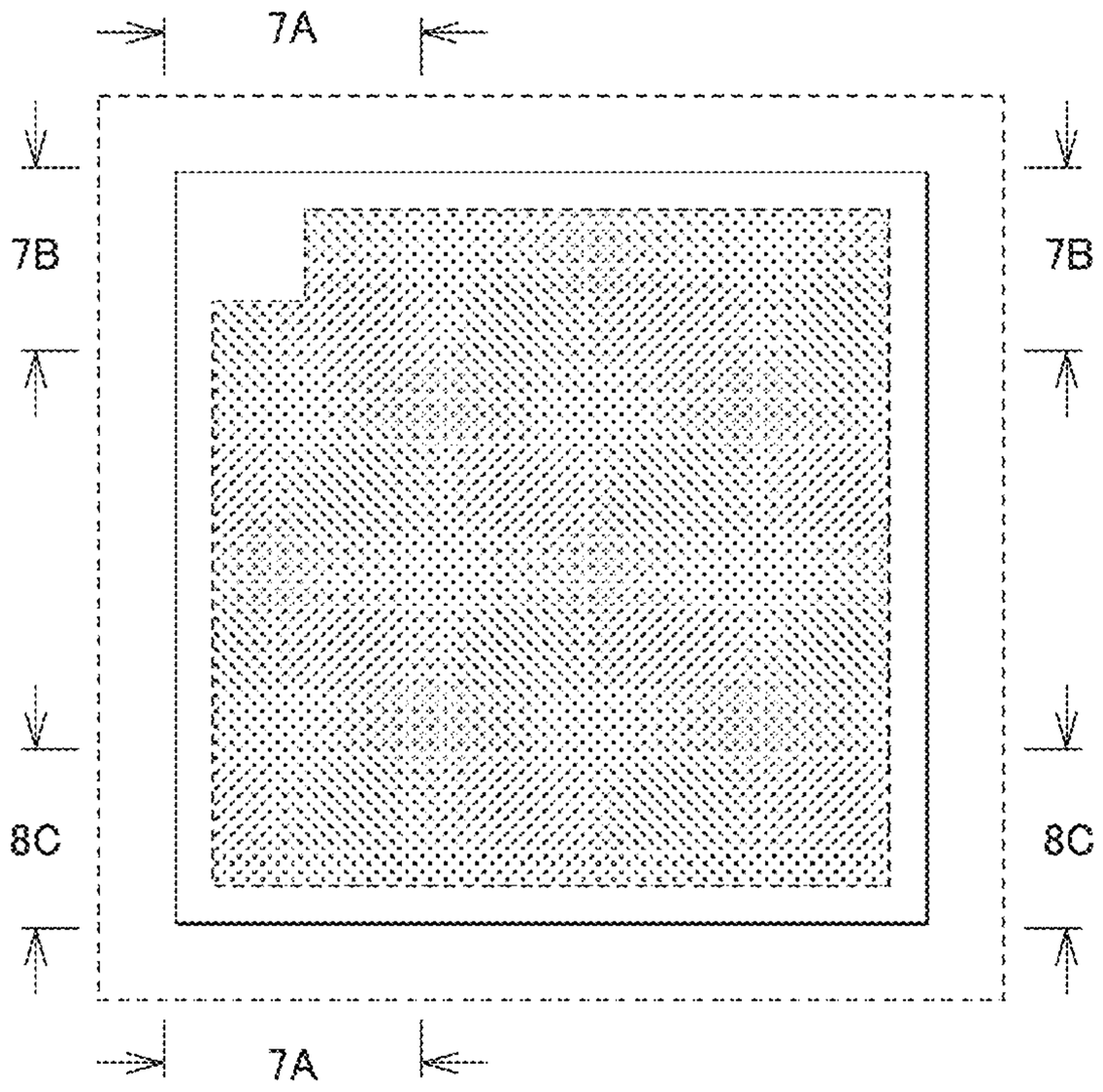

FIG.2

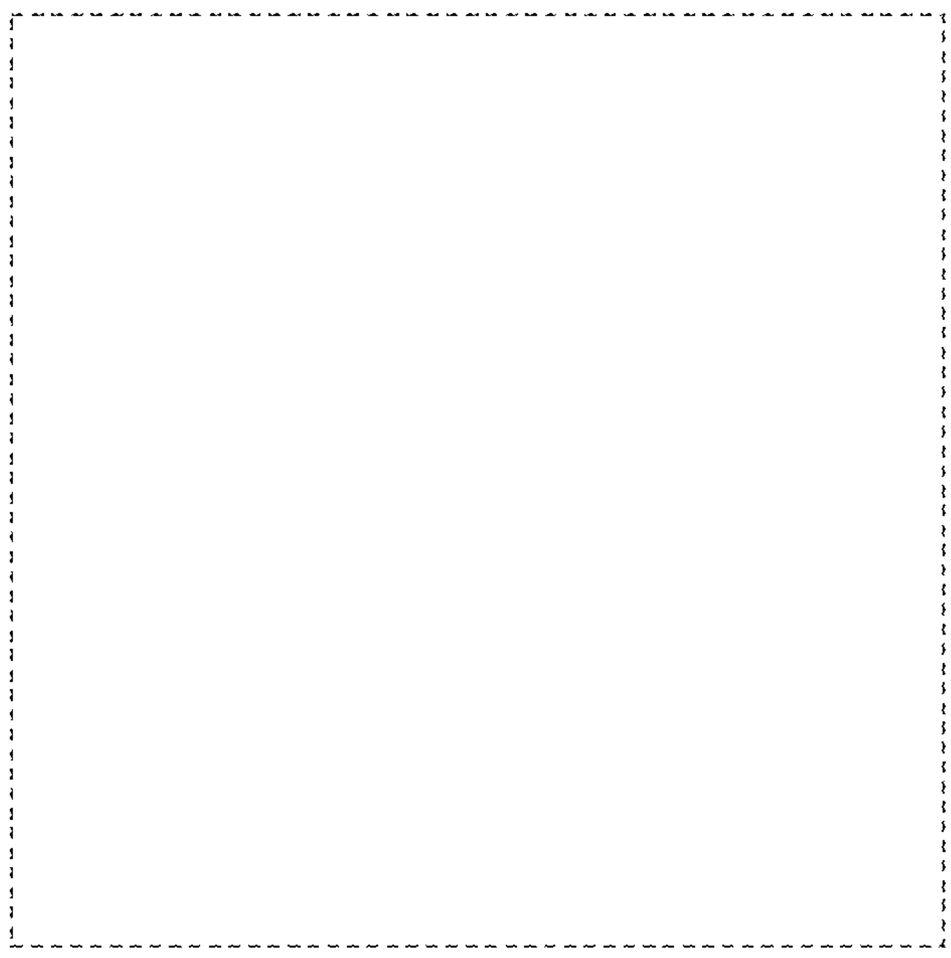

FIG.3

FIG.4

FIG.5

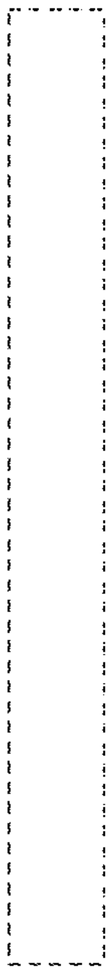

FIG.6

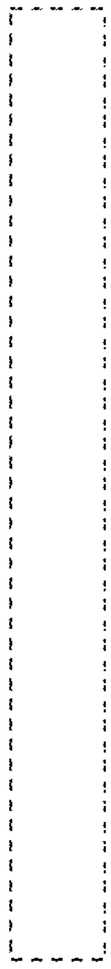

FIG.7

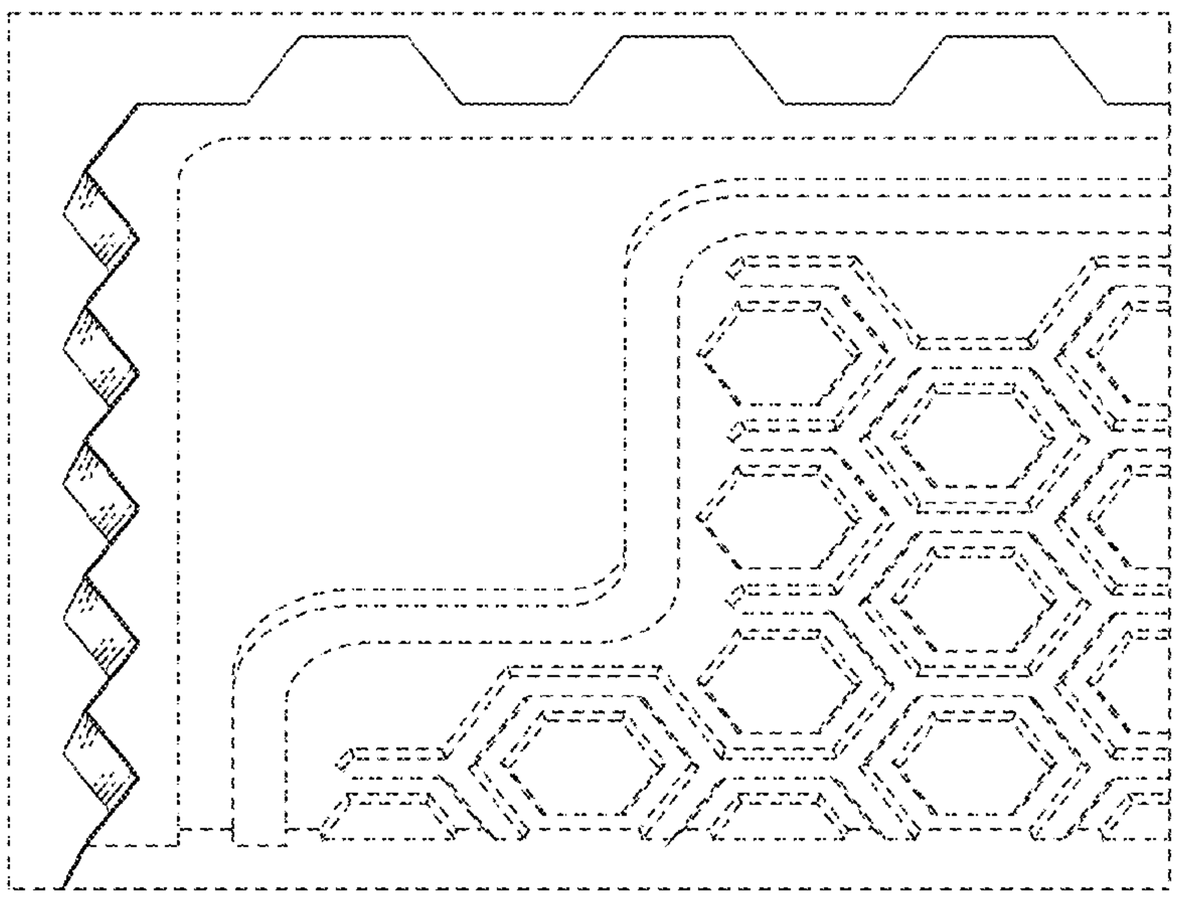

FIG.8